Document Number: MPXC2011DT1

Rev. 11, 09/2015



# MPXC2011DT1, 0 to 10 kPa, Differential, Compensated Pressure Sensor

Freescale Semiconductor has developed a high volume, miniature pressure sensor package which is ideal as a sub-module component or a disposable unit. The unique concept of the Chip Pak allows great flexibility in system design while providing an economic solution for the designer. This new chip carrier package uses Freescale Semiconductor's unique sensor die with its piezoresistive technology, along with the added feature of on-chip, thin-film temperature compensation and calibration.

#### **Features**

- Integrated temperature compensation and calibration
- · Ratiometric to supply voltage
- Polysulfone case material (ISO 10993)
- · Provided in easy-to-use tape and reel

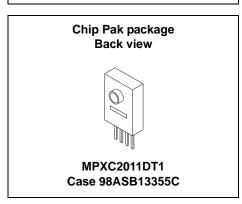
#### Typical applications

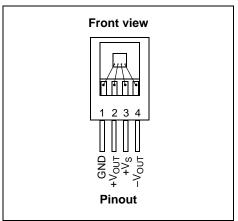
- · Respiratory diagnostics
- · Air movement control
- Controllers
- Pressure switching

#### **NOTE**

The die and wire bonds are exposed on the front side of the chip pak (pressure is applied to the backside of the device). Front side die and wire protection must be provided in the customer's housing. Use caution when handling the devices during all processes.

# MPXC2011DT1





Ordering Information						
Davies Name Chiming Backers			Pressure Type	Davies Marking		
Device Name	Shipping	Package	Gauge	Differential	Absolute	Device Marking
MPXC2011DTI	Tape and Reel	98ASB13355C		•		XXXX = Device code XXX = Trace code

Freescale reserves the right to change the detail specifications as may be required to permit improvements in the design of its products.

© 2010, 2012, 2014, 2015 Freescale Semiconductor, Inc. All rights reserved.





## Contents

1	General Description		
	1.1 Block diagram		
	1.2 Pinout		
	Mechanical and Electrical Specifications		
	2.1 Maximum ratings		
	2.2 Operating characteristics		
	Package Dimensions		
	3.1 Package description		
	Building History		

### **Related Documentation**

The MPXC2011DT1 device features and operations are described in a variety of reference manuals, user guides, and application notes. To find the most-current versions of these documents:

1. Go to the Freescale homepage at:

### http://www.freescale.com/

- 2. In the Keyword search box at the top of the page, enter the device number MPXC2011DT1.
- 3. In the Refine Your Result pane on the left, click on the Documentation link.

#### MPXC2011DT1



# 1 General Description

Freescale Semiconductor's MPXC2011DT1 Pressure Sensor has been designed for medical usage by combining the performance of Freescale Semiconductor's shear stress pressure sensor design and the use of biomedically approved materials. Materials with a proven history in medical situations have been chosen to provide a sensor that can be used with confidence in applications, such as invasive blood pressure monitoring. It can be sterilized using ethylene oxide. The portions of the pressure sensor that are required to be biomedically approved are the rigid housing and the gel coating.

The rigid housing is molded from a white, medical grade polysulfone that has passed extensive biological testing including: ISO 10993-5:1999, ISO 10993-10:2002, and ISO 10993-11:1993.

The MPXC2011DT1 contains a silicone dielectric gel which covers the silicon piezoresistive sensing element. The gel is a nontoxic, nonallergenic elastomer system which meets all USP XX Biological Testing Class V requirements. The properties of the gel allow it to transmit pressure uniformly to the diaphragm surface, while isolating the internal electrical connections from the corrosive effects of fluids, such as saline solution. The gel provides electrical isolation sufficient to withstand defibrillation testing, as specified in the proposed Association for the Advancement of Medical Instrumentation (AAMI) Standard for blood pressure transducers. A biomedically approved opaque filler in the gel prevents bright operating room lights from affecting the performance of the sensor.

## 1.1 Block diagram

Figure 1 shows a block diagram of the internal circuitry integrated on a pressure sensor chip.

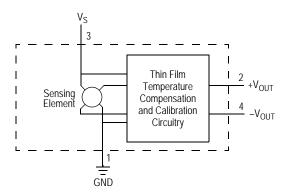


Figure 1. Block diagram

#### 1.2 Pinout

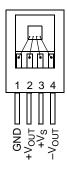


Figure 2. Device pinout (front view)

Table 1. Pin functions

Pin	Name	Function
1	GND	Ground
2	+V <sub>OUT</sub>	Output voltage
3	+V <sub>S</sub>	Voltage supply
4	-V <sub>OUT</sub>	Output voltage

MPXC2011DT1



# 2 Mechanical and Electrical Specifications

## 2.1 Maximum ratings

Table 2. Maximum ratings<sup>(1)</sup>

Rating	Symbol	Value	Unit
Maximum pressure (backside)	P <sub>max</sub>	75	kPa
Storage temperature	T <sub>stg</sub>	-25 to +85	°C
Operating temperature	T <sub>A</sub>	+15 to +40	°C

<sup>1.</sup> Exposure beyond the specified limits may cause permanent damage or degradation to the device.

### 2.2 Operating characteristics

Table 3. Operating characteristics ( $V_S = 10 V_{DC}$ ,  $T_A = 25 °C$  unless otherwise noted, P1 > P2)

Characteristic	Symbol	Min	Тур	Max	Unit
Pressure range <sup>(1)</sup>	P <sub>OP</sub>	0	_	10	kPa
Supply voltage <sup>(2)</sup>	Vs	_	3	10	V <sub>DC</sub>
Supply current	Io	_	6.0	_	mAdc
Full-scale span <sup>(3)</sup>	V <sub>FSS</sub>	24	25	26	mV
Offset <sup>(4)</sup>	V <sub>OFF</sub>	-1.0	_	1.0	mV
Sensitivity	ΔV/ΔΡ	_	2.5	_	mV/kPa
Linearity <sup>(5)</sup>	_	-1.0	_	1.0	%V <sub>FSS</sub>
Pressure hysteresis <sup>(5)</sup> (0 to 10 kPa)	_	_	±0.1	_	%V <sub>FSS</sub>
Temperature hysteresis <sup>(5)</sup> (+15 °C to +40 °C)	_	_	±0.1	_	%V <sub>FSS</sub>
Temperature effect on full-scale span <sup>(5)</sup>	TCV <sub>FSS</sub>	-1.0	_	1.0	%V <sub>FSS</sub>
Temperature effect on offset <sup>(5)</sup>	TCV <sub>OFF</sub>	-1.0	_	1.0	mV
Input impedance	Z <sub>IN</sub>	1300	_	2550	Ω
Output impedance	Z <sub>OUT</sub>	1400	_	3000	Ω
Response time <sup>(6)</sup> (10% to 90%)	t <sub>R</sub>	_	1.0	_	ms
Warm-up	_	_	20	_	ms
Offset stability <sup>(7)</sup>	_	_	±0.5	_	%V <sub>FSS</sub>

<sup>1. 1.0</sup> kPa (kilo Pascal) equals 0.145 psi.

- 4. Offset  $(V_{\mbox{\scriptsize OFF}})$  is defined as the output voltage at the minimum rated pressure.
- 5. Accuracy (error budget) consists of the following:

Linearity: Output deviation from a straight line relationship with pressure, using end point method, over the specified

pressure range.

Temperature Hysteresis: Output deviation at any temperature within the operating temperature range, after the temperature is cycled to and

from the minimum or maximum operating temperature points, with zero differential pressure applied.

Pressure Hysteresis: Output deviation at any pressure within the specified range, when this pressure is cycled to and from the minimum

or maximum rated pressure, at 25  $^{\circ}\text{C}.$ 

TcSpan: Output deviation at full rated pressure over the temperature range of 0 to 85 °C, relative to 25 °C.

TcOffset: Output deviation with minimum rated pressure applied, over the temperature range of 0 to 85 °C, relative to 25 °C.

- 6. Response Time is defined as the time for the incremental change in the output to go from 10% to 90% of its final value when subjected to a specified step change in pressure.
- 7. Offset stability is the product's output deviation when subjected to 1000 hours of Pulsed Pressure, Temperature Cycling with Bias Test.

#### MPXC2011DT1

<sup>2.</sup> Device is ratiometric within this specified excitation range. Operating the device above the specified excitation range may induce additional error due to device self-heating.

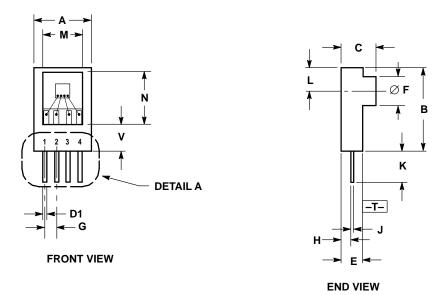
<sup>3.</sup> Full-scale span (V<sub>FSS</sub>) is defined as the algebraic difference between the output voltage at full rated pressure and the output voltage at the minimum rated pressure.

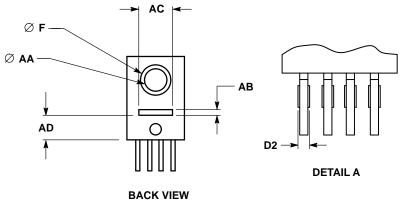


#### **Package Dimensions** 3

#### 3.1 Package description

This drawing is located at http://cache.freescale.com/files/shared/doc/package\_info/98ASB13355C.pdf.





- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH.

	INC	HES	MILLIN	IETERS	
DIM	MIN MAX		MIN	MAX	
Α	0.240	0.260	6.10	6.60	
В	0.350	0.370	8.89	9.40	
С	0.140	0.150	3.56	3.81	
D1	0.012	0.020	0.30	0.51	
D2	0.014	0.022	0.36	0.56	
Е	0.088	0.102	2.24	2.59	
F	0.123	0.128	3.12	3.25	
G	0.045	0.055	1.14	1.40	
Н	0.037	0.047	0.94	1.19	
J	0.007	0.011	0.18	0.28	
K	0.120	0.140	3.05	3.56	
L	0.095	0.105	2.41	2.67	
M	0.165	0.175	4.19	4.45	
N	0.223	0.239	5.66	6.07	
٧	0.105	0.115	2.67	2.92	
AA	0.095	0.107	2.41	2.72	
AB	0.015	0.035	0.38	0.89	
AC	0.120	0.175	3.05	4.45	
AD	0.100	0.115	2.54	2.92	

Case 98ASB1335C, Chip Pak package



# 4 Revision History

## Table 4. Revision history

Revision number	Revision date	Description
9	10/2012	Deleted references to device number MPXC2012DT (a no-gel option) throughout the document.
10	08/2014	Added pin descriptions and pin numbers.
11	09/2015	Corrected Block Diagram.     Updated format.



How to Reach Us:

Home Page: freescale.com

Web Support:

freescale.com/support

Information in this document is provided solely to enable system and software implementers to use Freescale products. There are no express or implied copyright licenses granted hereunder to design or fabricate any integrated circuits based on the information in this document.

Freescale reserves the right to make changes without further notice to any products herein. Freescale makes no warranty, representation, or guarantee regarding the suitability of its products for any particular purpose, nor does Freescale assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. "Typical" parameters that may be provided in Freescale data sheets and/or specifications can and do vary in different applications, and actual performance may vary over time. All operating parameters, including "typicals," must be validated for each customer application by customer's technical experts. Freescale does not convey any license under its patent rights nor the rights of others. Freescale sells products pursuant to standard terms and conditions of sale, which can be found at the following address: freescale.com/salestermsandconditions.

Freescale and the Freescale logos are trademarks of Freescale Semiconductor, Inc., Reg. U.S. Pat. & Tm. Off. All other product or service names are the property of their respective owners.

© 2010, 2012, 2014, 2015 Freescale Semiconductor, Inc.

Document Number: MPXC2011DT1

Rev. 11 09/2015



# **X-ON Electronics**

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Board Mount Pressure Sensors category:

Click to view products by NXP manufacturer:

Other Similar products are found below:

6407-249V-17343P 6407-250V-09273P 80527-25.0H2-05 80541-B00000150-01 80541-B00000200-05 80554-00700100-05 8056800300050-01 93.631.4253.0 93.731.4353.0 93.932.4553.0 136PC150G2 136PC15A1 142PC95AW71 142PC05DW70 15PSI-G-4V 180501A-L0N-B 26PCBKT 26PCCFA6D26 26PCCFS2G 26PCCVA6D 93.632.7353.0 93.731.3653.0 93.931.4853.0 93.932.4853.0 SCDA120XSC05DC 185PC30DH 20INCH-G-MV-MINI 26PCAFJ3G 26PCCEP5G24 26PCDFA3G 26PCJEU5G19 ASCX15AN-90
TSCSAAN001PDUCV DCAL401DN DCAL401GN XZ202798SSC XZ203676HSC 6407-249V-09343P 6407-250V-17343P SP370-25-1160 81794-B00001200-01 HSCDLNN100PGAA5 82681-B00000100-01 81618-B00000040-05 SSCDJNN015PAAA5 TSCDLNN100MDUCV
TSCSAAN100PDUCV NBPDANN015PGUNV NBPLLNS150PGUNV 142PC100D